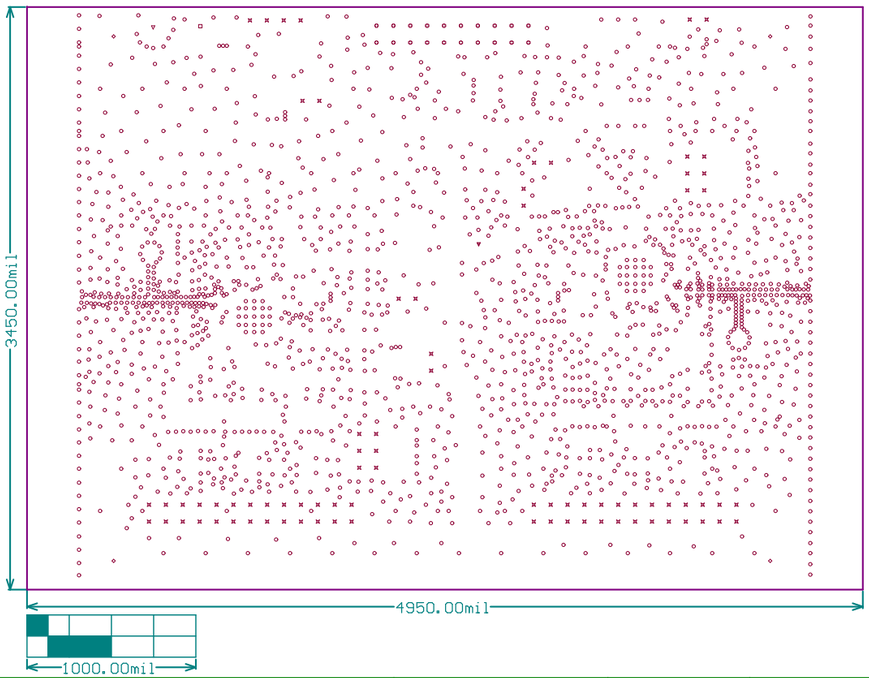
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.00mil	3.4	
1	Top Layer		1.60mil		
	Dielectric 1	FR-4 High Tg	5.00mil	4.6	
2	Signal Layer 1		1.40mil		
	Dielectric 2	FR-4 High Tg	44.00mil	4.6	
3	Signal Layer 2		1.40mil		
	Dielectric 3	FR-4 High Tg	5.00mil	4.6	
4	Bottom Layer		1.60mil		
	Bottom Solder	Solder Resist	1.00mil	3.4	
	Bottom Overlay				
Total board thickness:			62.00mil		

Notes
RF Nets must maintain 50ohm characteristic impedance +/-10%
RF nets are GCPW lines with 6.5mil width and ~6.25mil gap to GND



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
◇	4	118.11mil (3.000mm)	NPTH	Round	Top Layer - Bottom Layer	
○	1970	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
▼	1	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
○	3	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	+/-11.81mil
⊠	80	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
✪	20	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	+/-7.87mil
□	1	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
▽	1	98.43mil (2.500mm)	PTH	Round	Top Layer - Bottom Layer	
	2080 Total					

DESIGN INFORMATION

MIN. TRACK WIDTH: 6.5 MIL
MIN. CLEARANCE: 5 MIL
MIN. VIA PAD SIZE: 11.457 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-4 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [ ] 20-30 um [X] OTHER 36 um

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [ ] GREEN [X] OTHER RED
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: WBMS BCU EVM
DESIGNED FOR: Public Release
FILE NAME: MCU122A.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: MCU122	REV: A	SVN REV: Not in version control
LAYER NAME = [illegible] Dimensions	TID #:		
PLOT NAME = Fabrication Drawing	GENERATED : 1/27/2026 3:51:28 PM	TEXAS INSTRUMENTS	

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ENGINEER: a0504388	LAYOUT BY: .PCB_Layout
SCALE: 1.00	ALTIUM DESIGNER VERSION: 26.2.0.7